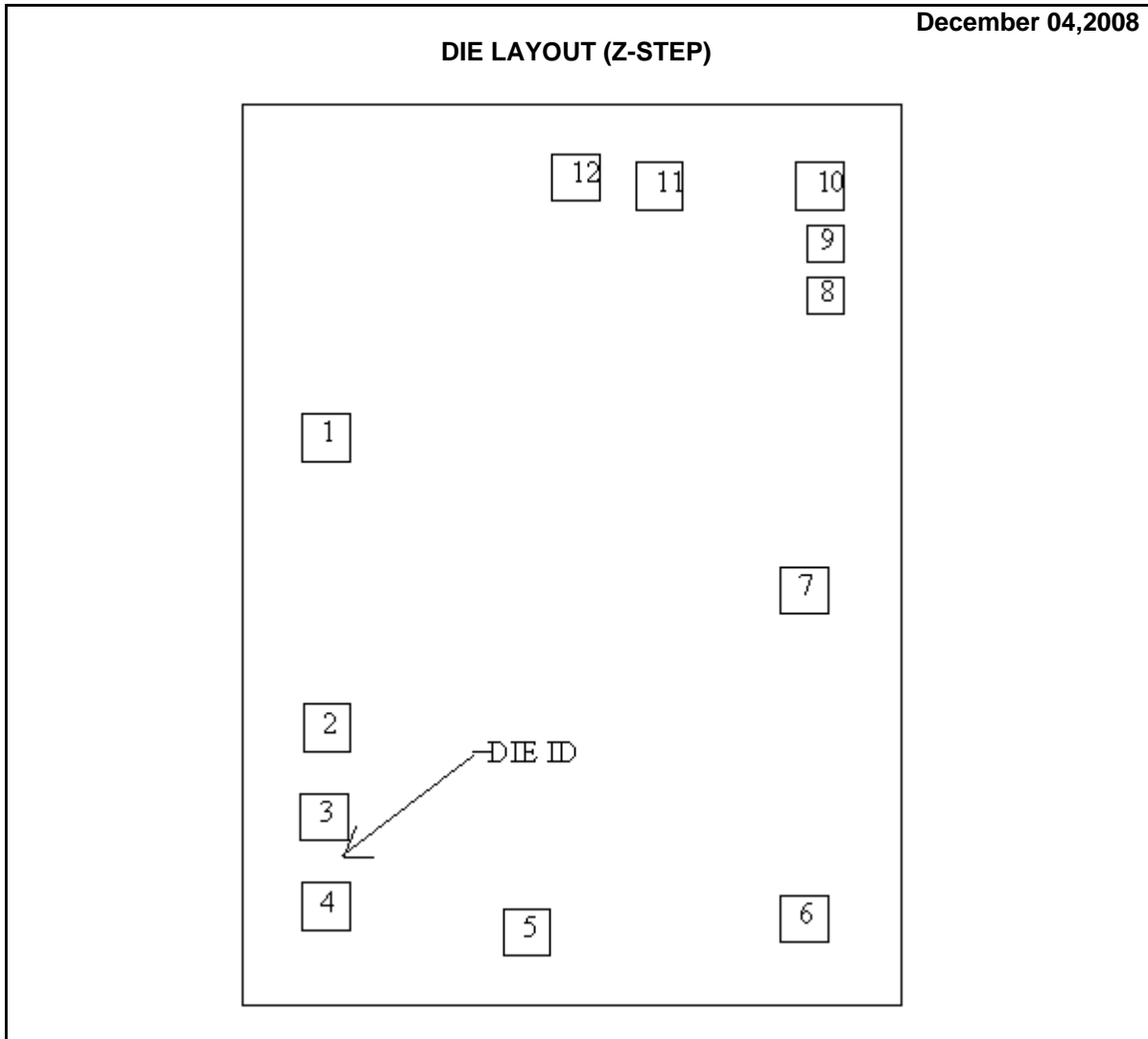


**DS16F95 MDR MCD1160A
EIA-485/EIA-422A DIFFERENTIAL BUS TRANSCEIVERS**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	M176Z	Bond Pad Opening Size (min)	114 μ m x 114 μ m
Die Step	Z	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	125mm	Back Side Metal	Bare Back
Die Size (Drawn)	1600 μ m x 2184 μ m 63.0mils x 86.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	215 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (Z -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE	
		X	Y	X	Y
R0	1	-596	285	114	x 114
/RE	2	-593	-420	114	x 114
DE	3	-602	-637	114	x 114
DI	4	-596	-853	114	x 114
GND	5	-110	-916	114	x 114
IN/OUT A	6	563	-883	114	x 114
IN/OUT B	7	563	-85	114	x 114
NC	8	615	628	89	x 89
NC	9	615	755	89	x 89
NC	10	602	895	114	x 114
NC	11	211	894	114	x 114
VCC	12	9	916	114	x 114

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